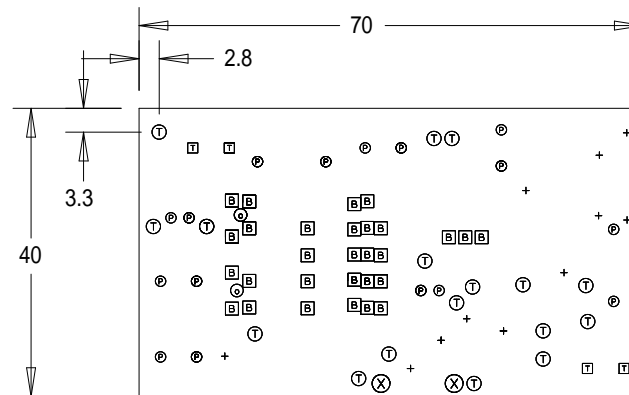


SPEC:


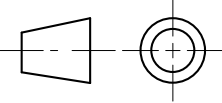
COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)		
BOARD THICKNESS		1.6mm /63mils	
STACKUP	DFTM /2LAYERS		
MINIMAL GAP		150um /6.0mils	
MINIMAL SLIVER		150um /6.0mils	
COPPER THICKNESS		35um(1oz)at START	
FINISH THICKNESS	CHEMICAL NiAu		
SOLDER MASK		GREEN TOP&BOT	
SILKSCREEN	WHITE TOP&BOT		
ALL BOARD ELECTRICALLY TESTED			
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK			

For outline details use gerber



DRILL CHART: TOP to BOTTOM			
ALL UNITS ARE IN MILLIMETERS			
FIGURE	SIZE	PLATED	QTY
+	0.5 VIA	PLATED	11
⊙	0.8	PLATED	16
⊕	1.0	PLATED	17
⊗	1.1	PLATED	2
⊠	1.2	PLATED	29
⊡	1.4	PLATED	4
⊙	1.6	PLATED	2

			W03/2019
indice	Description		Date
Controle par :		Autorise par:	
 ON semiconductor Board: NCP/NVC1362 EVB -A-TLS	Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE		
	Subc. DYPE TECH	Dessine: e B	
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